

Part Number

Customer

Category	Parameter	Specification	Measurement Method	
OverallWafer	1.0	Diameter	100.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	{110} +/- 1 degree	Customer supplied material
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Customer supplied material
	4.0	Secondary Flat Orientation	none or SEMI Standard	Customer supplied material
	5.0	Overall Thickness	336.00 +/- 7.00 μ m	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<3.00 μ m	Guaranteed by Process
	7.0	Bow	<60.00 μ m	ADE to ASTM F534, 100%
	8.0	Warp	<60.00 μ m	ADE to ASTM F534, 100%
	9.0	Edge Chips	0	Bright Light, 100%
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Customer supplied material
	12.0	Handle Orientation	{100} +/- 0.5 degree	Customer supplied material
	13.0	Handle Thickness	300.00 +/- 5.00 μ m	ADE, 100%
	14.0	Handle Doping Type	P	Customer supplied material
	15.0	Handle Dopant	Boron	Customer supplied material
	16.0	Handle Resistivity	0.01-0.05 Ohm-cm	Customer supplied material
	17.0	Backside Finish	Polished with oxide and lasermark	Guaranteed by process
BuriedOxide	18.0	Oxide Type	Thermal	
	19.0	Oxide Thickness	10,000.00 +/- 500.00 A	Nanospec centre point, 4%
	20.0	Oxide formed on	Device and/or Handle	
DeviceSilicon	21.0	Device Growth Method	CZ	Customer supplied material
	22.0	Device Orientation	{100} +/- 0.5 degree	Customer supplied material
	23.0	Nominal Thickness	35.00 +/- 2.00 μ m	ADE single point, 100% (note3)
	24.0	Distance to device silicon edge from wafer edge	< 2mm	Typical by Process
	25.0	Device Doping Type	P	Customer supplied material
	26.0	Device Dopant	Boron	Customer supplied material
	27.0	Device Resistivity	0.01-0.02 Ohm-cm	Customer supplied material
	28.0	Surface Voids	None	Bright Light, 100% (note2)
	29.0	Haze	None	Bright Light, 100% (note2)
	30.0	Scratches	none on the front-side	Bright Light, 100% (note2)

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Shipping Details	Wafer per box :	Max 25
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness



Explanatory Notes 1. Microscope inspection performed using microscope scan as below. 5x objective.

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information